Silicon N Channel MOS FET High Speed Power Switching

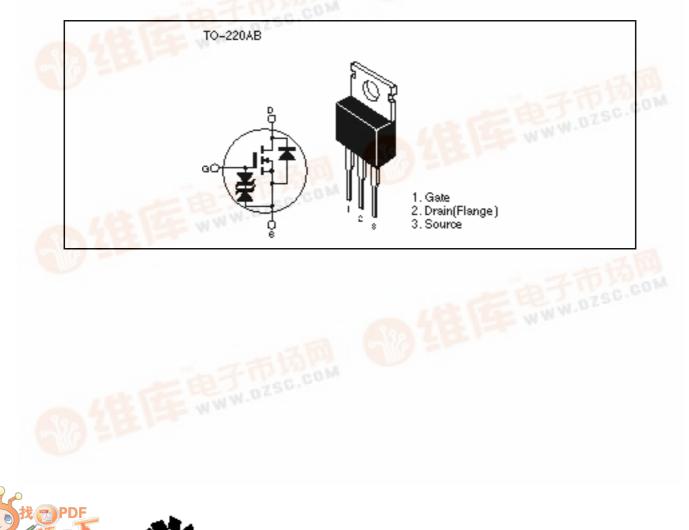


ADE-208-551 Target Specification 1st. Edition

#### Features

- Low on-resistance
- $R_{DS} = 0.040$  typ.
- High speed switching
- 4V gate drive device can be driven from 5V source

#### Outline



#### **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

Item	Symbol	Ratings	Unit	
Drain to source voltage	V <sub>DSS</sub>	60	V	
Gate to source voltage	V <sub>GSS</sub>	±20	V	
Drain current	I <sub>D</sub>	15	А	
Drain peak current	↓ → 1 D(pulse)	60	А	
Body to drain diode reverse drain current	l <sub>DR</sub>	15	А	
Avalanche current	l* <sup>3</sup>	15	А	
Avalanche energy	E <sub>AR</sub> * <sup>3</sup>	19	mJ	
Channel dissipation	Pch*2	40	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	
Natary A DW/ 40mm duty availar 4.0/				

Notes: 1. PW 10 $\mu$ s, duty cycle 1 %

2. Value at Tc = 25°C

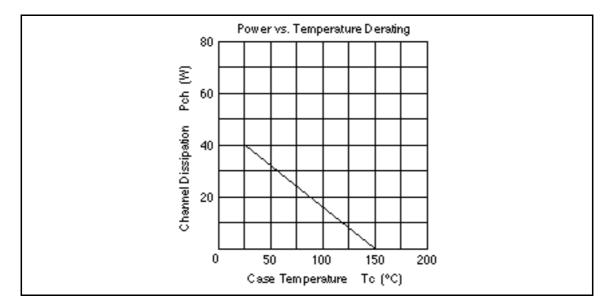
3. Value at Tch =  $25^{\circ}$ C, Rg 50

## **Electrical Characteristics** (Ta = $25^{\circ}$ C)

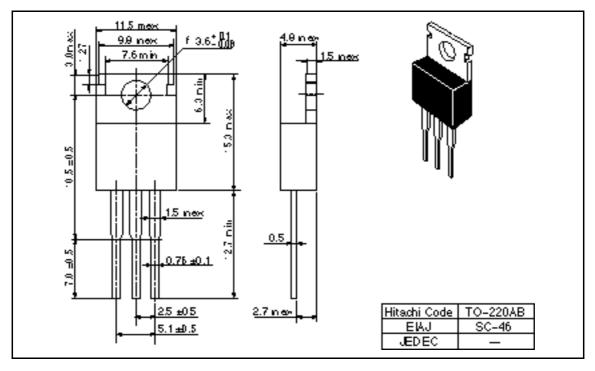
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{\rm (BR)DSS}$	60			V	$I_{\rm D} = 10 {\rm mA}, V_{\rm GS} = 0$
Gate to source breakdown voltage	$V_{(\text{BR})\text{GSS}}$	±20			V	$I_{g} = \pm 100 \mu A, V_{DS} = 0$
Gate to source leak current	I <sub>GSS</sub>	—		±10	μA	$V_{GS} = \pm 16V, V_{DS} = 0$
Zero gate voltege drain current	I <sub>DSS</sub>	_	—	10	μA	$V_{\rm DS} = 60  \text{V},  V_{\rm GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.5		2.5	V	$I_{\rm D} = 1 {\rm mA}, V_{\rm DS} = 10 {\rm V}$
Static drain to source on state	$R_{DS(on)}$	—	0.040	0.052		$I_{\rm D} = 8A, V_{\rm GS} = 10V^{*1}$
resistance	R <sub>DS(on)</sub>	_	0.060	0.105		$I_{\rm D} = 8A, V_{\rm GS} = 4V^{*1}$
Forward transfer admittance	y <sub>fs</sub>	10	16	_	S	$I_{\rm D} = 8A, V_{\rm DS} = 10V^{*1}$
Input capacitance	Ciss	_	500		pF	$V_{DS} = 10V$
Output capacitance	Coss	_	260	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	—	110	_	pF	f = 1MHz
Turn-on delay time	t <sub>d(on)</sub>	_	10	_	ns	$I_{\rm D} = 8A, V_{\rm GS} = 10V$
Rise time	t <sub>r</sub>	_	80		ns	R <sub>L</sub> = 3.75
Turn-off delay time	t <sub>d(off)</sub>	_	100	_	ns	
Fall time	t <sub>f</sub>	_	110	_	ns	
Body to drain diode forward voltage	$V_{DF}$	—	0.9		V	$I_{F} = 15A, V_{GS} = 0$
Body to drain diode reverse recovery time	t <sub>rr</sub>	—	50	_	ns	I <sub>F</sub> = 15A, V <sub>GS</sub> = 0 diF/ dt = 50A/μs
Note: 1. Pulse test						

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#### **Main Characteristics**



#### **Package Dimentions**



Unit: mm

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